AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Serial Number: 10/774,923

Filing Date: February 9, 2004

Title: DIRECT BUILD-UP LAYER ON AN ENCAPSULATED DIE PACKAGE HAVING A MOISTURE BARRIER STRUCTURE

Assignee: Intel Corporation

IN THE SPECIFICATION

Please amend the specification as follows:

The paragraph beginning at page 1, after the title, is amended as follows:

RELATED APPLICATIONS

The application is a divisional of U.S. Patent Application Serial No. 09/660,757, filed September 13, 2000, now issued as U.S. Patent No. 6,713,859, which is incorporated herein by reference.